USB 2.0 Video

PC Camera Controller

SN9C2272M

Datasheet

Document No.:

Version: v1.20

For the latest data sheet, please visit www.sunnywale.com

Revision	Date	Description
0.01	2018-11-16	Draft Release
0.02	2018-11-22	Update block diagram
1.00	2020-02-07	Add ESD Information
1.10	2020-07-07	Modify core power to 1.2V
1.20	2020-07-27	Modify Pin-out Diagram
Apply to		SN9C2272MJG

Table of Contents

1 General Description

The SN9C2272M is a USB 2.0 High-Speed (HS) compatible PC camera controller. The low power design provides extreme low consumption on device standby, operation and even high performance state. The low thermal design gets the module operating temperature inside platform under reasonable range. The SN9C2272M is fully compliant with USB Video Class. The OS systems supported are including Windows 7, Windows 8, and Windows 10.

The new generation image signal processing engine brings sight video experience. The high performance Motion-JPEG compression engine makes variant compression ratio to consider bandwidth requirement well which output MJPG data format. It is also a high performance and high speed transmission engine on YUV un-compression data format. With the integrated sensor interface and color processing engine, it can supports most available CMOS sensors that range from VGA to QXGA. It is controlled by the embedded micro-controller and the statistics for 3A (AE / AWB / AF) are built-in.

To decrease the BOM cost and PCB area, the SN9C2272M integrates 2 voltage regulators for sensor power. One is for analog part and the other is for I/O power. Futhermore, the built-in Clock Synthesizer for performance and power saving makes an external crystal is not needed.

The QFN32 3x6mm package dimension is also for the thin design. The flexible architecture is consisted of mask ROM, internal RAM and external serial-flash which can store the customized codes and parameters. With the highly-integrated firmware architecture and the developing kit provided by SONiX, it's easy for 3rd party to fulfill customized features.

2 Features

2.1 System

- 3.3V, 1.2V power supply are necessary (Core power 1.1V provide by Backend IC)
- Extreme low power consumption, < 30mA when standby and < 0.5mA when suspend (Power consumption of sensor is not included)
- Built-in Clock Synthesizer for performance and power saving
- Built-in PLL for internal clock generation
- Using external serial flash to store customized code and data
- No external RAM needed
- 1.8V output power source to supply CMOS sensor's I/O power

- 2.8V output power source to supply CMOS sensor's analog power(2.7V~3.3V control by FW setting) or 1.2V output power source to supply CMOS sensor's core power
- QFN package of 32-pins

2.2 USB Controller

- USB 2.0 high-speed and full-speed compatible
- USB Video Class 1.1 compliant
- USB 2.0 HS/FS auto sense and switch
- USB FS mode and USB disconnection are programmable
- USB Low Power Management Sleep State with RTD3
- 5 endpoints: 1 CONTROL pipe, 2 Interrupt IN , 1 Bulk IN (Video stream) and 1 Isochronous-IN (MJPEG/YUY2 video stream)
- 6 alternate settings for Video Streaming Interface

2.3 Sensor Interface

- Support QXGA(3.0MP, 2048x1536), FHD(2.0MP, 1920x1080), UXGA(2.0MP, 1600x1200), SXGA(1.3MP, 1280x1024), HD(1.0MP, 1280x720), VGA(0.3MP, 640x480) CMOS ISP sensor
- MIPI-CSI2 interface supported
- Support Y8, YUY2 and RAW (Bayer-Pattern) image data format from sensor
- Output clock: 480/(m*n) MHz output clock request of CMOS sensor silicon.
- Up to 96Mhz pixel clock is acceptable
- Support industrial standard 2-wire serial interface for sensor control

2.4 Color processing

- AE histogram statistics
- AWB window statistics
- AF edge window statistics
- On-the fly defect-pixel cancellation
- Lens shading compensation for R/G/B channel
- Low pass filter
- Individual digital color gain control for R/Gr/Gb/B channels
- Individual digital color gain control for Y/Cb/Cr channels
- Pixel offset (optical black) compensation for R/Gr/Gb/B channels
- Programmable gamma table for RGB channels
- Programmable color conversion matrix for R/G/B input

- Configurable noise reduction
- De-color aliasing in Edge
- Configurable edge enhancement
- Programmable gamma table for Y channel
- Configurable windowing function after processed image
- Programmable hue and saturation
- Auto Gamma for backlight preview
- Auto Frequency for MSOC
- Auto de-flicker
- Wide Dynamic Range (WDR)
- Vertical lens distortion correction (VLDC)

2.5 Scaling Engine

- Scale down on Y/Cb/Cr
- For QXGA / UXGA / SXGA / VGA sensors, combined scaling and windowing function provides similar view angle for QXGA / FHD / UXGA / SXGA / HD / SVGA / VGA / CIF / QVGA / QCIF / QQVGA output format
- Fine scaling(128/m, m:128 ~ 2047)

2.6 Line OSD

- Displays Up to 4 Rows x 24 Characters with independent start position
- Character Size HxV: 16x16, 16x24
- Line zoom (x1, x2, x3, x4 to x8 for both X and Y coordinates)
- Character with transparency and other 3 color choices.
- 64 different user definable characters can be stored in RAM.

2.7 JPEG Encoder

- JPEG YUV422 baseline format
- Built-in JPEG encoder support USB Video Class MJPEG payload
- 128 bytes quantization tables for Y and C provide programmable compression ratio
- Support frame level bite rate control mechanism

2.8 Video / Still Image

- Output video / still image format:

- USB Video Class Uncompressed YUY2 payload (16bits/pixel)
- USB Video Class MJPG payload

- Video streaming up to 30fps@FHD at USB2.0 high-speed mode.
- Still Image capture up to QXGA and is able to support UVC still image capture method 1/2

2.9 Frame rate

- Frame rate considering USB bandwidth limitation

	Normal Resolution @ USB High-Speed									
Format	QXGA	FHD	UXGA	SXGA	HD	SVGA	VGA	CIF	QVGA	QCIF
YUY2	3fps	5fps	6fps	9fps	12fps	25fps	30fps	30fps	60fps	60fps
MJPEG	24fps	30fps	30fps	60fps	60fps	120fps	120fps	120fps	120fps	120fps

- Frame rate considering sensor characteristic

  The maximum frame rate is limited by how many fps that sensor can output under acceptable maximum pixel clock

2.10 GPIO

- 3 GPIOs are predefined as following functions including LED control, serial flash write protect, sensor reset.
- 1 GPIO is reserved for customized application.

2.11 Micro Controller and USB Device Features

- Built-in 8032 micro controller with 6K bytes data memory, and CPU clock rate is up to 120MHz
- Load extended F/W up to 128KB from external serial flash.
- Load VID/PID, manufacturer, product and serial number string from external serial flash.
- Load UVC parameter definition from external serial flash.
- F/W is upgradeable from PC
- Force USB at FS mode / Force USB disconnect
- Interrupt at the end of H/W windowing
- Watch dog supported

2.12 Pre-Defined for USB Video Class

- Brightness control (UVC defined)
- Contrast control (UVC defined)
- Hue control (UVC defined)

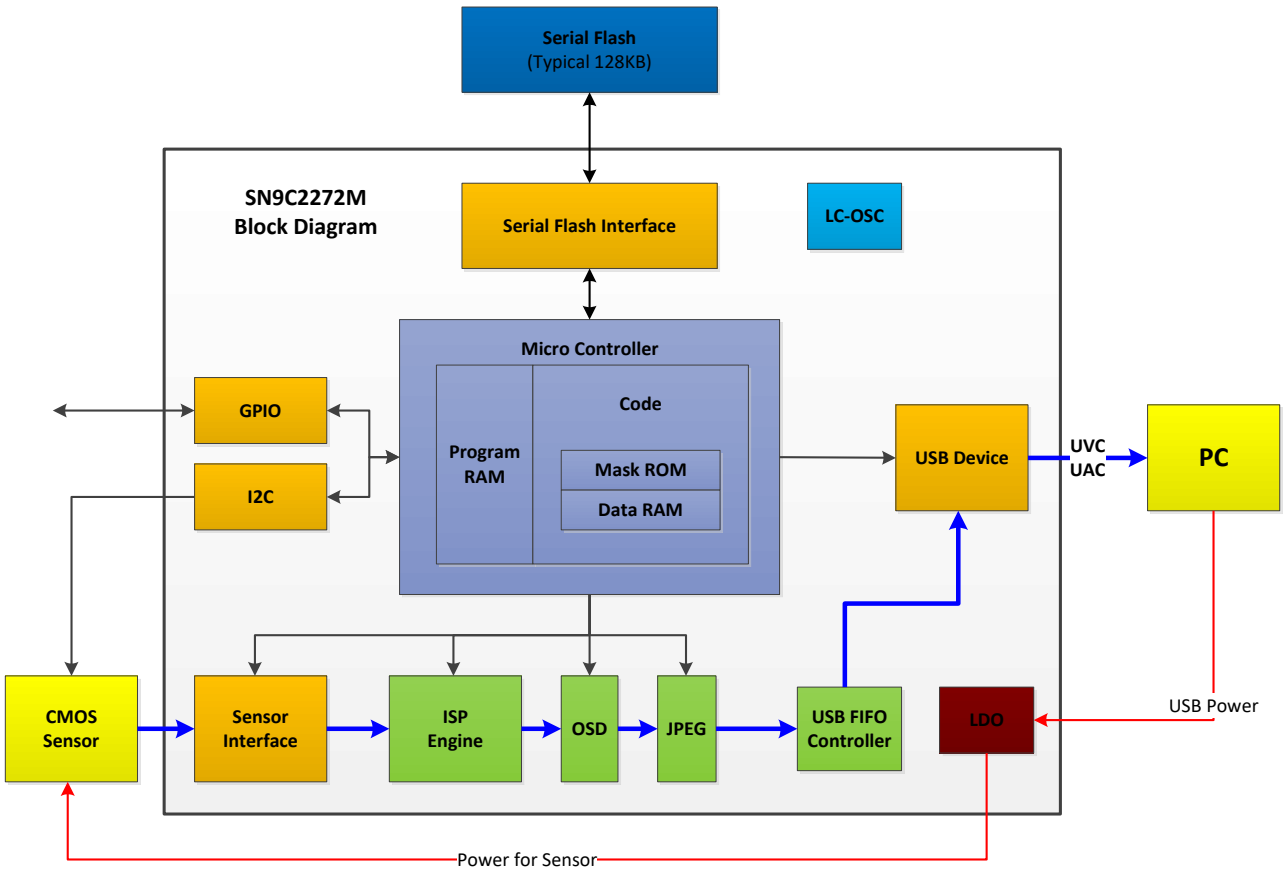
- Saturation control (UVC defined)
- Sharpness control (UVC defined)
- Gamma control (UVC defined)
- Privacy control (UVC defined)
- LED indicator on video streaming
- UVC Extension unit support

2.13 Platform Support

- Microsoft Window 7 32 & 64 bit, Microsoft Window 8/8.1 32 & 64 bit, Microsoft Window 10 32 & 64 bit
- Mac - OS X 10.4.8 or later
- Linux with UVC driver (open source available at http://linux-uvc.berlios.de/)

3 Function Block Diagram

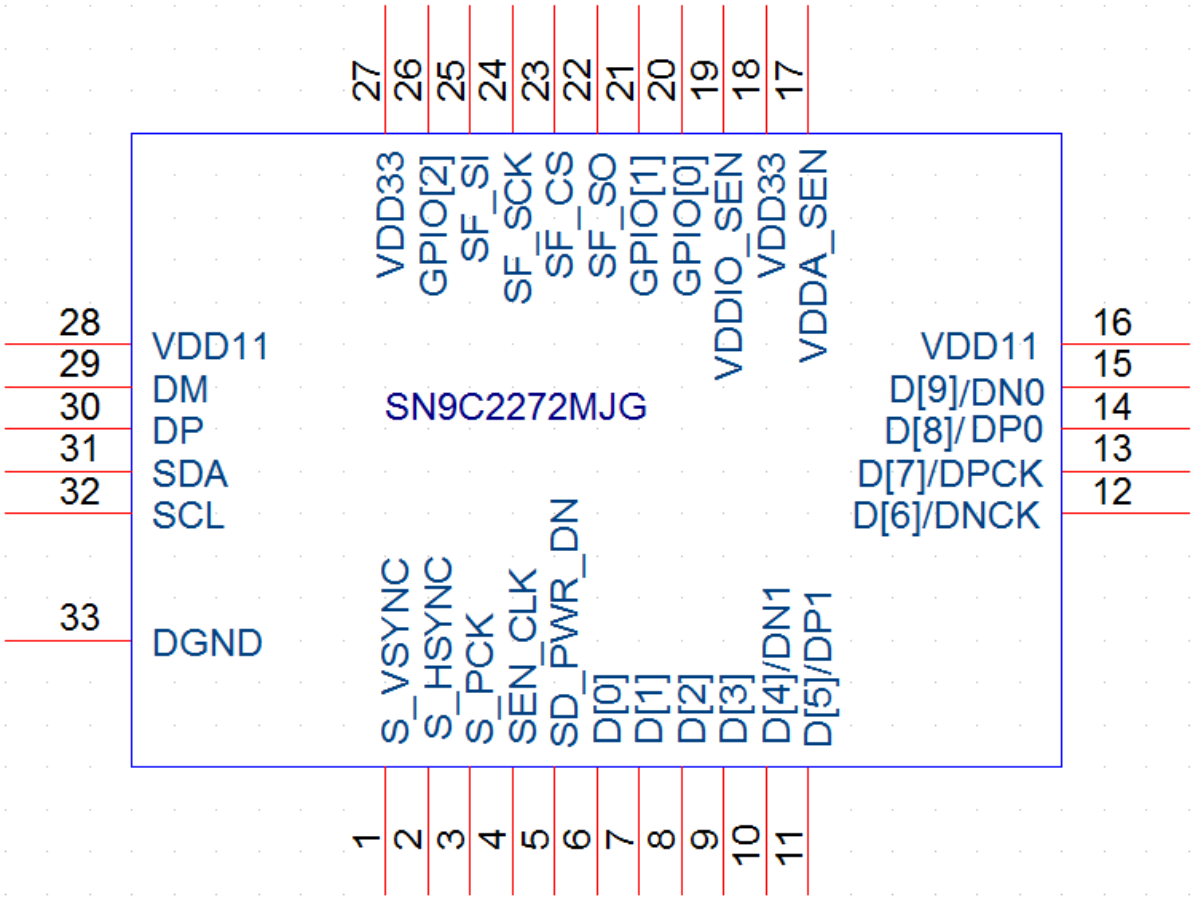
3.1 Block Diagram



4 Pin Assignment

4.1 SN9C2272MJG – 32 pins QFN

4.1.1 Pin-out Diagram



4.1.2 Pin Description

Pin No.	Pin Name	Description
1	S_VSYNC	Sensor vsync
2	S_HSYNC	Sensor hsync
3	S_PCK	Sensor pixel clock
4	SEN_CLK	Sensor clock
5	SD_PWR_DN	General purpose I/O
6	D0	Sensor image data
7	D1	Sensor image data
8	D2	Sensor image data

9	D3	Sensor image data
10	D4/DN1	Sensor image data or MIPI data lane1 N
11	D5/DP1	Sensor image data or MIPI data lane1 P
12	D6/DNCK	Sensor image data or MIPI clock lane N
13	D7/DPCK	Sensor image data or MIPI clock lane P
14	D8/DP0	Sensor image data
15	D9/DN0	Sensor image data
16	VDD11	Internal LDO VOUT for DSP core power
17	VDDA_SEN	Internal LDO VOUT for sensor analog power
18	VDD33	Internal LDO VIN
19	VDDIO_SEN	Internal LDO VOUT for sensor IO power
20	GPIO_0	General purpose I/O
21	GPIO_1	General purpose I/O
22	SF_SO	SPI data out to serial flash
23	SF_CS	Chip select to serial flash
24	SF_SCK	Clock to serial flash
25	SF_SI	SPI data in from serial flash
26	GPIO_2	General purpose I/O
27	VDD33	DSP system power
28	VDD11	1.1V DSP core power
29	DM	D- for USB
30	DP	D+ for USB
31	SDA	I²C data
32	SCL	I²C clock

5 Electrical Characteristics

5.1 DC operating Condition

5.1.1 Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
VDD33	Power Supply	-0.3 ~ 3.6	V
VDD33_18	Power Supply	-0.3 ~ 3.6	V
DVDD	Power Supply	-0.12 ~ 1.32	V
Vin	Input Voltage	-0.3 ~ VDD33 + 0.3	V
Vout	Output Voltage	-0.3 ~ VDD33 + 0.3	V

ESD (Electrostatic Discharge ESD) Susceptibility Voltage			
	Human Body Model (HBM)	Machine Model (MM)	Charged-Device Model (CDM)
All Pin	≧4000V	≧200V	≧500V

5.1.2 Recommended Operating Conditions

Symbol	Parameter	Typ	Units
VDD33	Power Supply	3.3	V
VDD33_18	Power Supply	3.3/1.8	V
DVDD	Power Supply	1.2	V
Vin	Input voltage	3.3	V

5.1.3 Low Dropout Regulator Electrical Characteristics

(Under Recommended Operating Conditions and VDD33=3.0 ~ 3.6V, Ta=-20 to +70 °C)

Symbol	Parameter	Typ	Units
VDDA1	Power Supply for 2.8V LDO	3.3	V
VO275	Voltage output of 2.8V LDO	2.85	V
IO275	Output current capacity of 2.8V LDO	100	mA
VDD33	Power Supply for 1.8V LDO	3.3	V
VO180	Voltage output of 1.8V LDO	1.85	V
IO180	Output current capacity of 1.8V LDO	150	mA

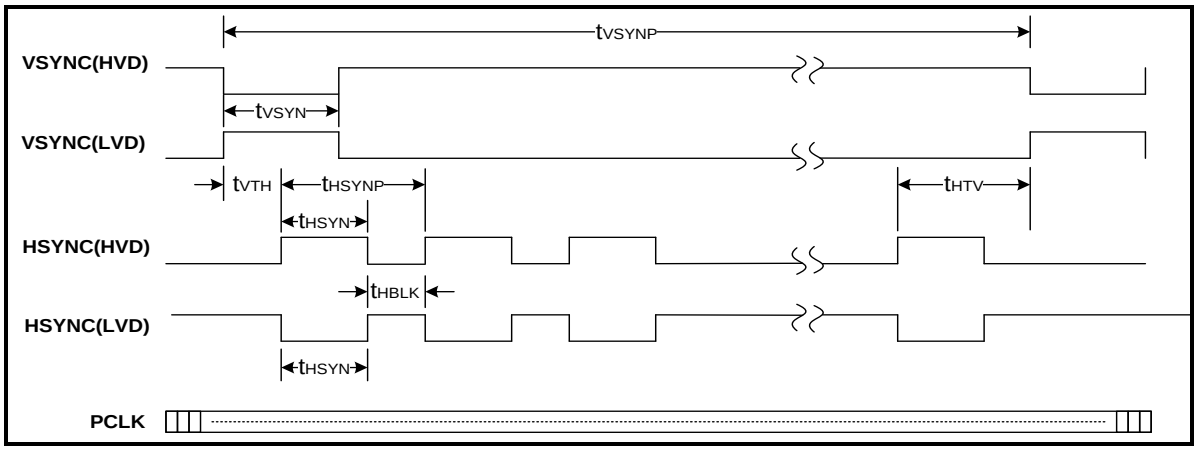
5.1.4 DC Electrical Characteristics

(Under Recommended Operating Conditions and VDD33=3.0 ~ 3.6V, VDD33_18=1.62 ~ 3.6V, Ta=0 to +70 °C)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Vil (VDD33)	Input low voltage	CMOS	-0.3		0.2*VDD33	V
Vih(VDD33)	Input high voltage	CMOS	0.8*VDD33		VDD33+0.3	V
Vil (VDD33_18)	Input low voltage	CMOS	-0.3		0.2*VDD33_18	V
Vih(VDD33_18)	Input high voltage	CMOS	0.8*VDD33_18		VDD33_18+0.3	V
Iil	Input low current	no pull-up or pull-down	-1		1	μA
Iih	Input high current	no pull-up or pull-down	-1		1	μA
Ioz	Tri-state leakage current		-1		1	μA
Vol	Output Low voltage	Iol=4mA / 8mA			0.4	V
Voh	Output high voltage	Ioh=4mA / 8mA	2.4			V
Cin	Input capacitance			10		pF
Cout	Output capacitance			10		pF
Cbid	Bi-directional buffer Capacitance			10		pF
Rpu	Pull-up resistor			70K		Ω
Rpd	Pull-down resistor			70K		Ω

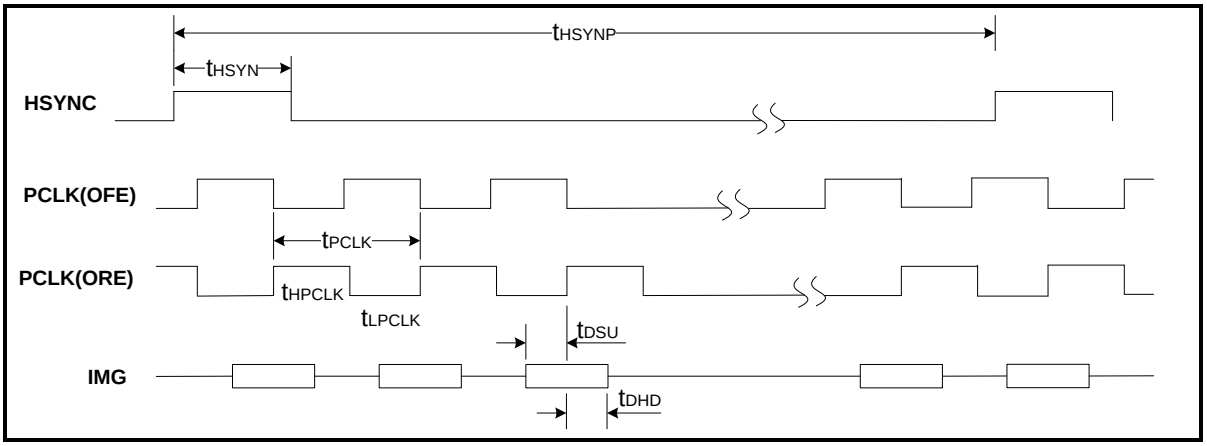
5.2 AC operating Condition

5.2.1 Parallel Sensor Interface



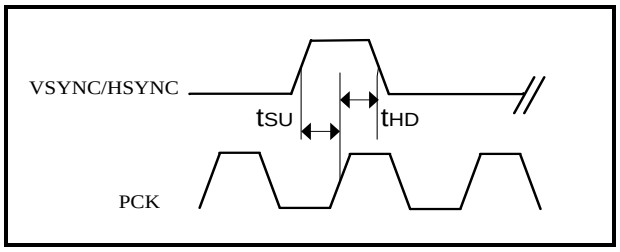
Parameter	Symbol	Min.	Typ.	Max.	Unit
VSYNC pulse width	tVSYNC	tPCLK	-	-	ns
VSYNC to HSYNC	tVTH	tPCLK	-	-	ns
HSYNC pulse width	tHSYN	tPCLK	-	-	ns
Blank time between two HSYNC	tHBLK	tPCLK	-	-	ns
HSYNC to VSYNC	tHTV	tHSYNP			ns
Note: tSENCK is period of internal clock for sensor post processing. tHSYNP is period of Hsync, tVSYNP is period of Vsync. HVD (High Valid), LVD (Low Valid).					

SYNC_MODE = 1 : (PCLK is free run)



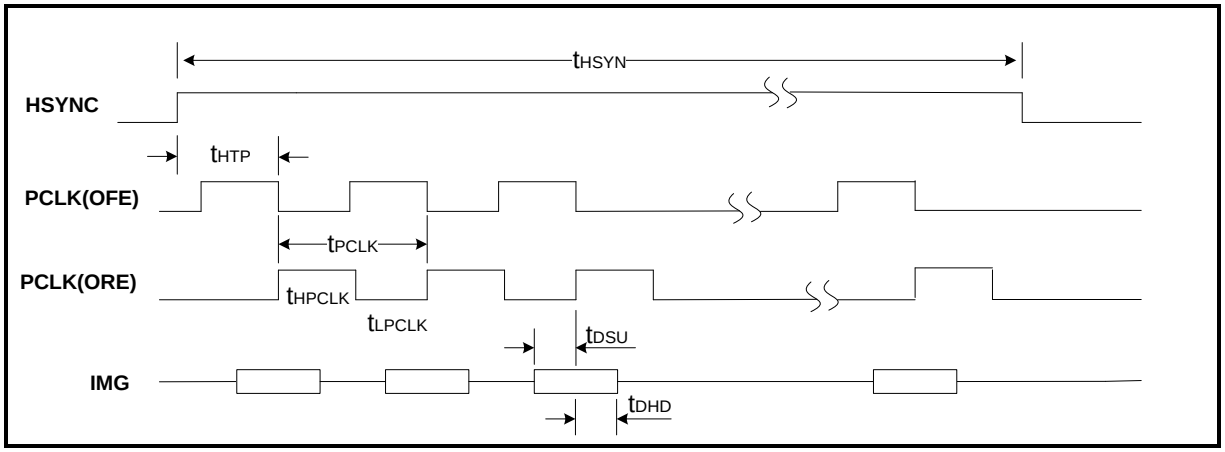
Parameter	Symbol	Min.	Typ.	Max.	Unit
HSYNC pulse width	tHSYN	tPCLK	-	-	ns
PCLK Low Pulse Width	tLPCLK	2.0	-	-	ns
PCLK High Pulse Width	tHPCLK	2.0	-	-	ns

Frequency of pixel clock	fPCLK	-	-	96	MHz
Image data setup time	tDSU	2.0	-	-	ns
Image data hold time	tDHD	2.0	-	-	ns
Note: tSENCK is period of internal clock for sensor post processing ORE (On Rising Edge) means the timing act on rising edge OFE (On Falling Edge) means the timing act on falling edge					



Parameter	Symbol	Min.	Typ.	Max.	Unit
VSYNC / HSYNC setup time	tSU	2	-	-	ns
VSYNC / HSYNC hold time	tHD	2	-	-	ns

SYNC_MODE = 0 : (PCLK is output only when hsync active)



Parameter	Symbol	Min.	Typ.	Max.	Unit
HSYNC pulse width	tHSYN	HSIZE * tPCLK	-	-	ns
HSYNC to PCLK	tHTP	tSENCK	-	-	
PCLK Low Pulse Width	tLPCLK	2.0	-	-	ns

PCLK High Pulse Width	tHPCLK	2.0	-	-	ns
Frequency of pixel clock	fPCLK	-	-	96	MHz
Image data setup time	tDSU	2.0	-	-	ns
Image data hold time	tDHD	2.0	-	-	ns
Note: tSENCK is period of internal clock for sensor post processing ORE (On Rising Edge) means the timing act on rising edge OFE (On Falling Edge) means the timing act on falling edge HSIZE represents total valid PCLK number per horizontal line					

5.2.2 MIPI RX Electrical Characteristics

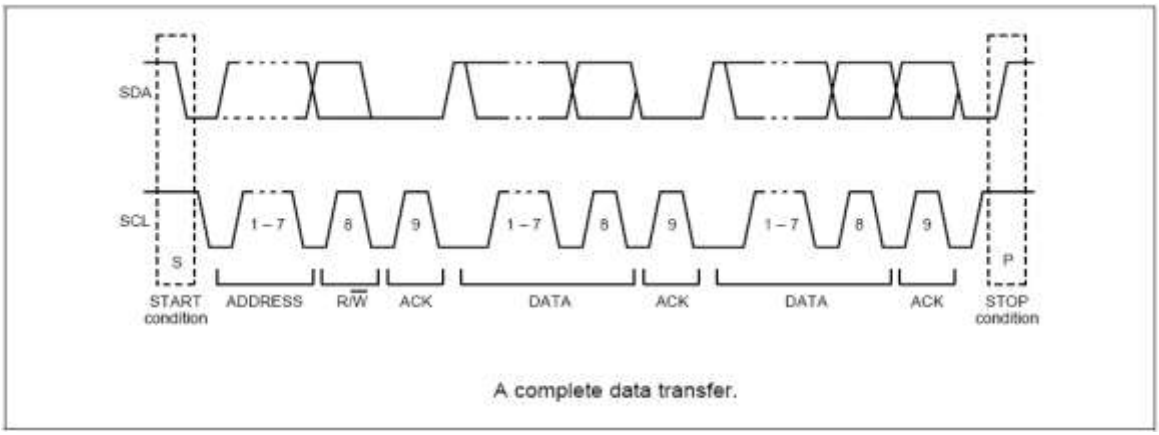
Low power mode electrical characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VIH	Logic 1 input voltage	880			mV
VIL	Logic 0 input voltage, not in ULP state			550	mV
VHYST	Input hysteresis	25			mV

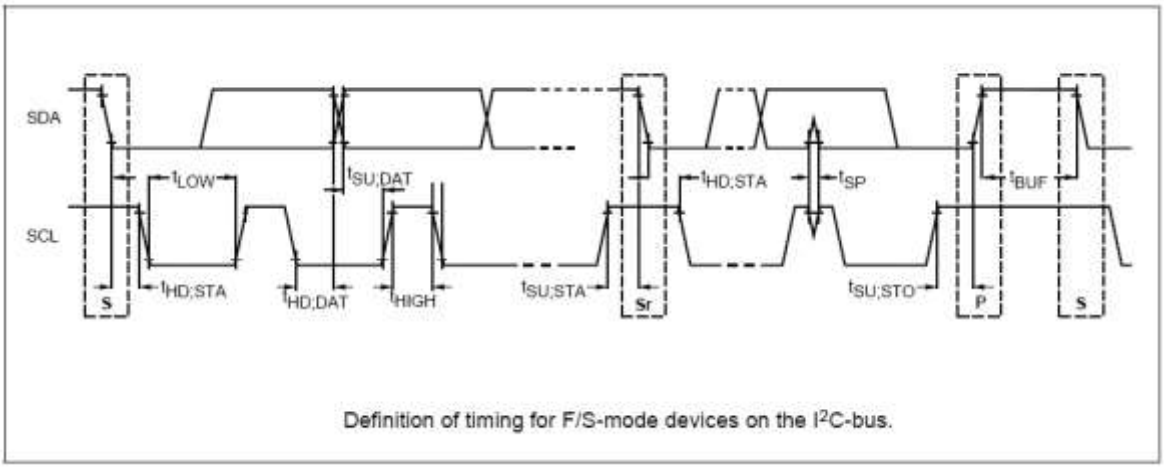
High speed mode electrical characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VCMRX(DC)	Common mode voltage		200		mV
VID	Differential input voltage		200		mV
ZID	Differential input impedance	80		125	Ω

5.2.3 I2C Control Interface



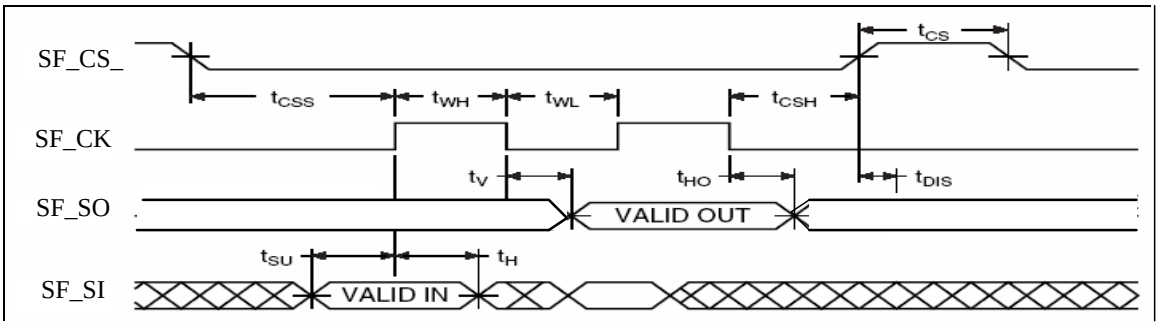
A complete data transfer.



Definition of timing for F/S-mode devices on the I²C-bus.

Parameter	Symbol	Standard mode			Fast mode			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
SCL clock frequency	f_{SCL}	-	98.7	-	-	394.7	-	kHz
Hold time START condition	$t_{HD;STA}$	-	5067	-	-	1267	-	ns
LOW period of the SCL clock	t_{LOW}	-	5067	-	-	1267	-	ns
HIGH period of the SCL clock	$t_{HD;STA}$	-	5067	-	-	1267	-	ns
Setup time for a repeated START condition	$t_{SU;STA}$	-	5067	-	-	1267	-	ns
Data hold time: Write	$t_{HD:DAT}$	-	2533	-	-	633	-	ns
Data hold time: Read	$t_{HD:DAT}$	10	-	-	10	-	-	ns
Data setup time: Write	$t_{SU:DAT}$	-	2533	-	-	633	-	ns
Data setup time: Read	$t_{SU:DAT}$	10	-	-	10	-	-	ns
Setup time for STOP condition	$t_{SU:STO}$	-	5066	-	-	1267	-	ns
Bus free time between a STOP and START condition	t_{BUF}	4.8	-	-	1.4	-	-	us

5.2.4 Serial Flash Interface



When f_{SCK} = 60 Mhz (SFCK_SEL=1, SPEED=1)

Parameter	Symbol	Min.	Typ.	Max.	Unit
SCK clock frequency	f_{SCK}	-	60	-	MHz
Chip Select low to SF_CK Edge	t_{CSS}	136		-	ns
SF_CK Edge to Chip Select High	t_{CSH}	32		-	ns
Chip High period	t_{CS}	120		-	ns
Clock high period	t_{WH}	8	-	-	ns
Clock low period	t_{WL}	8	-	-	ns
Input Data setup time	t_{SU}	6	-	-	ns
Input Data hold time	t_{H}	106	-	-	ns
Output Data Valid time @ CL=20pF	t_{V}	-	-	5	ns
Output Data Hold time @ CL=20pF	t_{HO}	0	-	-	ns

When f_{SCK} = 24 Mhz (SFCK_SEL=0, SPEED=1)

Parameter	Symbol	Min.	Typ.	Max.	Unit
SCK clock frequency	f_{SCK}	-	24	-	MHz
Chip Select low to SF_CK Edge	t_{CSS}	36		-	ns
SF_CK Edge to Chip Select High	t_{CSH}	36		-	ns
Chip High period	t_{CS}	41.67		-	ns
Clock high period	t_{WH}	20.83	-	-	ns
Clock low period	t_{WL}	20.83	-	-	ns
Input Data setup time	t_{SU}	10	-	-	ns
Input Data hold time	t_{H}	10	-	-	ns
Output Data Valid time @ CL=20pF	t_{V}	-	-	5	ns
Output Data Hold time @ CL=20pF	t_{HO}	36	-	-	ns

5.3 Temperature

5.3.1 Storage Temperature

From -40℃ to +150℃

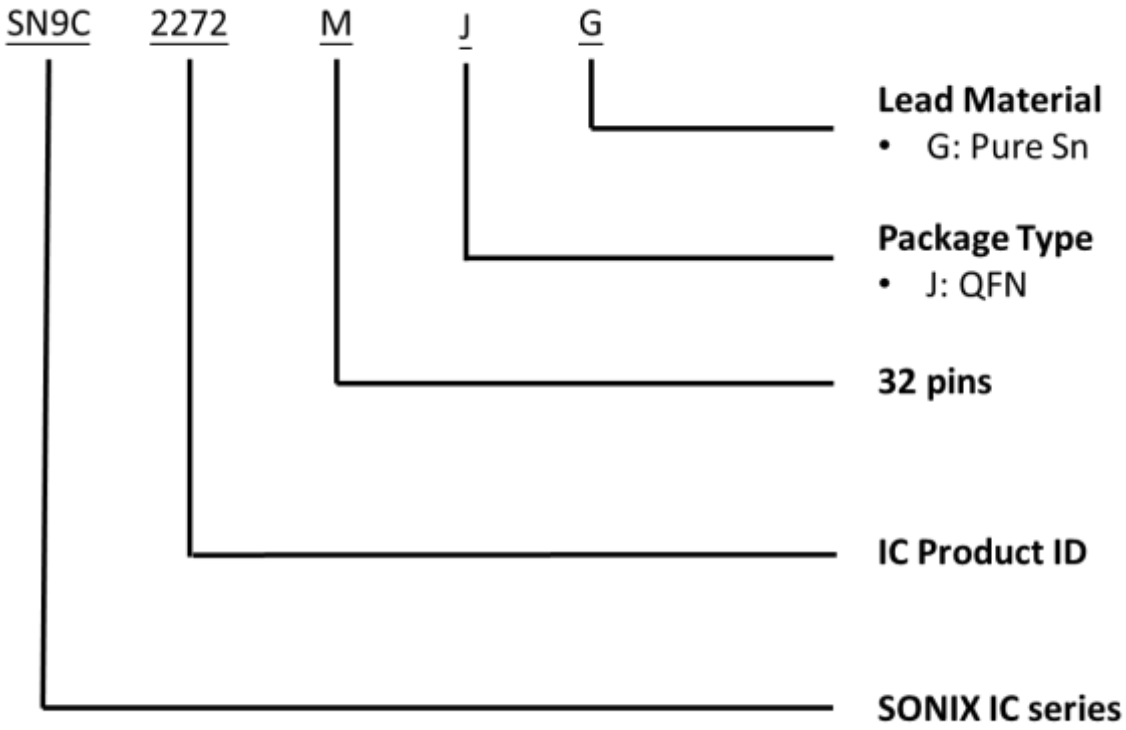
5.3.2 Operation Temperature

Max. Junction Temp (℃)	Max. Lead Temp.	Ta (℃)	Θja (℃/W)
125	+390℃±10℃, 5sec	-20 ~ 70	52.5

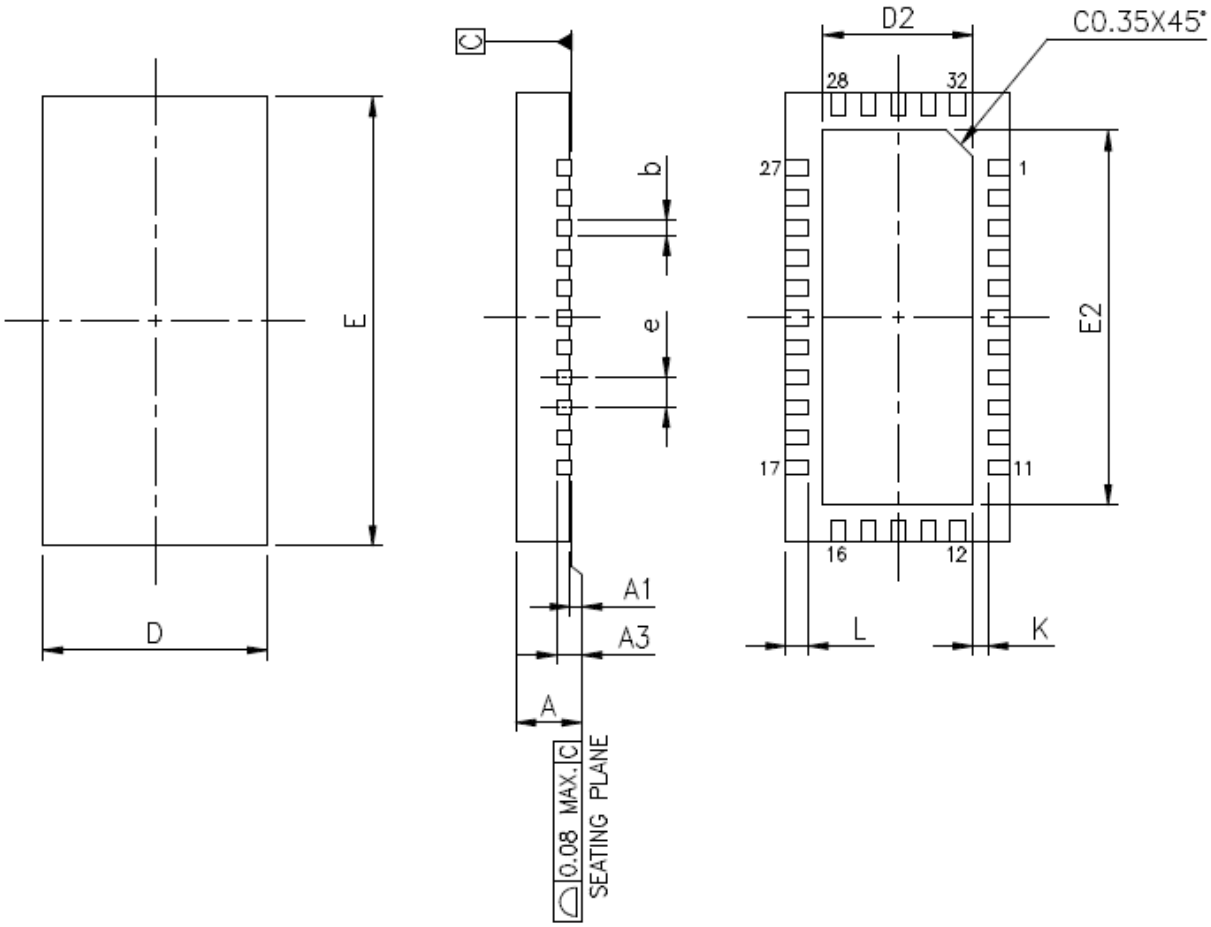
6 Package Information

6.1 Nomenclature

Example:



6.2 32 pins QFN



	PACKAGE TYPE					
JEDEC OUTLINE	N/A					
PKG CODE	WQFN(X332)			VQFN(N/A)		
SYMBOLS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.80	0.85	0.90
A1	0.00	0.02	0.05	0.00	0.02	0.05
A3	0.203 REF.			0.203 REF.		
b	0.15	0.20	0.25	0.15	0.20	0.25
D	3.00 BSC			3.00 BSC		
E	6.00 BSC			6.00 BSC		
e	0.40 BSC			0.40 BSC		
L	0.20	0.30	0.40	0.20	0.30	0.40
K	0.20	—	—	0.20	—	—

	E2			D2			LEAD FINISH		JEDEC CODE
PAD SIZE	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	Pure Tin	PPF	
83X201 MIL	4.90	5.00	5.05	1.90	2.00	2.05	X	V	N/A

7 Contact Information

- Corporate Headquarters
  10F-1, No.36, Taiyuan Street, Chupei City, Hsinchu, Taiwan
  TEL: (886)3-5600-999 FAX: (886)3-5600-888
  E-mail: http://www.sonix.com

- Taipei Sales Office
  15F-2, No.171 Song Ted Road, Taipei, Taiwan
  TEL: (886)2-2759-1999 FAX: (886)2-2759-8111
  E-mail: markt@sonix.com, sale@sonix.com

- Hong Kong Sales Office
  Unit No.705,Level 7 Tower 1,Grand Central Plaza 138 Shatin Rural Committee Road, Shatin, New Territories, Hong Kong
  TEL: (852)2723-8088FAX: (852)2723-9199
  E-mail: hksale@sonix.com

- Shenzhen Contact Office
  High Tech Industrial Park, Shenzhen, China
  TEL: (86)755-8304-5321 FAX: (86)755-8301-5321
  E-mail: awin@sunnywale.com

- U.S.A. Sales Office
  TEL: 401-9492666 FAX: 401-9492888
  E-mail: asscungiosonix@att.com